

CTB Programme

Hybrids, MCM, Interconnection and Micropackaging WG

3rd Technical Presentations Day

ESTEC

3rd May 2006



Hybrids, MCM, Interconnection, Micropack. WG



CENTRE NATIONAL D'ETUDES SPATIALES

CTB Programme

Hybrids, MCM, Interconnection and Micropackaging WG

Agenda

- **10:00 - 10:15- Introduction** by Alberto Boetti - ESTEC TEC-QCT and Claude Drevon – Chairman CTB WG Hybrids
- **10:15 – 10:45 - Review of AAS-ETCA power hybrid technologies – Applications to DC/DC converters -** Benoît Goffin – AAS ETCA- Charleroi
- **11:00 – 11:30 - Use of MCM-Smart HTCC technology – Application to Astrium Space Digital Products (DSP, ERC32 Microcomputer etc.)** Brigitte Braux – EADS Astrium- Velizy
- **11:45 – 12:15 - Status of MCGA packages for ATMEL space products – Development of MCM products (Memories etc.)** Dominique De Saint Roman - Atmel- Nantes
- **Lunch**
- **13:30 – 14:00 - Evaluation of a HDI Demonstrator Module with CSP and BGA packages -** Nadia Wazad – EADS Astrium- Velizy
- **14:15 – 14:45 - Development of RF switches MEMS using LTCC technology** Sergio Di Nardo - AAS- L'Aquila
- **15:00 – 15:30 - Microwave organic PCBs for space applications** Claude Drevon - AAS - Toulouse
- **15:45 - 16:15 – Conclusions and General Discussion**